

Abstract of the Disclosure:

An electronic component and a method for populating a circuit carrier during the production of the electronic component includes providing the semiconductor chip with at least one
5 buffer body on its active top side, which buffer body, during the populating method, protects the semiconductor component structures - disposed under the buffer body - of the active top side of the semiconductor chip against mechanical damage and has a protective layer of a mechanically damping material.

GLM/kf